



AB L3&L4 v1.1.3 - 0.5mm 5-layer Board with Microvias

Material Selection

Halogen-free FR-4
Permittivity @ 100MHz:
Permittivity @ 1GHz:
Loss Tangent @ 100MHz:
Loss Tangent @ 1GHz:
Lead Free Assembly Compatible

Solder resist colour: green
Silkscreen print colour: white

Surface Finish

On top and bottom layer surfaces:
electroless nickel immersion gold

Non-standard Tolerances

Holes sized 0.2mm may be plugged by plating. These are all vias.
For them we do not care the finished hole sizes.

Board Layer Stack

Cu 18um*	Prepreg UT47-1080 60um	01	_____
Cu 35um	Core UT47 76um	02	_____
Cu 35um	Prepreg UT47-1080 60um	03	_____
Cu 35um	Core UT47 76um	04	_____
Cu 18um*	Prepreg UT47-1080 60um	05	_____

*35um final after plating

Total Laminated Thickness: 0.5mm +/- 0.05mm !

Drill Layer-Pairs

_____	01	_____	Top Layer	.gtl
_____	02	_____	Plane 1 (GND)	.gp1
_____	03	_____	Mid Layer 1	.gl
_____	04	_____	Plane 2 (GND)	.gp2
_____	05	_____	Bottom Layer	.gbl

Layer Name Gerber

Top Paste Mask	.gtp
Top Overlay	.gto
Top Solder Mask	.gts
Board Outline	.gm1

Holes / Drilling

Drill files contain finished hole diameters
Drilling layer pairs: 1-2, 1-5

Board Outline

Contour routed with break-away tabs

Element Counts

(for reference only)

Components: 41
Nets: 88
Pads: 548
Tracks: 1873
Polygons: 25
Holes: 434
Vias: 354

Controlled Impedance Reference

Diff. trace width/space on top layer (microstrip) 75 ohms +/- 10% : 0.125/0.1mm

Diff. trace width/space on top and bottom layer (microstrip) 60 ohms +/- 10% : 0.125/0.1mm